



Material Content Data Sheet



Sales Product Name	SAK-TC237LP-32F200S AC			Issued		18. August 2019		
MA#	MA001677586							
Package	PG-LFBGA-292-6			Weight*		932.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.859	1.06	1.06	10576	10576
wire	noble metal	palladium	7440-05-3	0.014	0.00		15	
	non noble metal	copper	7440-50-8	1.407	0.15	0.15	1509	1524
encapsulation	organic material	carbon black	1333-86-4	0.732	0.08		785	
	plastics	epoxy resin	-	50.476	5.41		54143	
	inorganic material	silicondioxide	60676-86-0	314.563	33.74	39.23	337414	392342
substrate	plastics	epoxy resin	-	6.479	0.70		6950	
	inorganic material	bariumsulfate	7727-43-7	9.942	1.07		10664	
	plastics	acrylic resin	-	11.506	1.23		12341	
	inorganic material	aluminiumhydroxide	21645-51-2	53.265	5.71		57135	
	plastics	epoxy bismaleimide triazine resin	-	61.156	6.56		65599	
	inorganic material	glass fibre	-	82.857	8.89		88876	
	non noble metal	copper	7440-50-8	196.577	21.09	45.25	210857	452422
plating	noble metal	gold	7440-57-5	1.106	0.12		1186	
	non noble metal	nickel	7440-02-0	3.027	0.32	0.44	3247	4433
solderball	noble metal	silver	7440-22-4	4.457	0.48		4781	
	non noble metal	tin	7440-31-5	122.898	13.18	13.66	131826	136607
glue	plastics	epoxy resin	-	0.489	0.05		524	
	noble metal	silver	7440-22-4	1.466	0.16	0.21	1572	2096
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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